



AEC-Q200

This component was always
RoHS compliant from the first
date of manufacture.

- Surface Mount 3.0 x 3.0 mm Package
- Complies with Directive 2002/95/EC (RoHS)

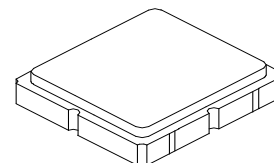


Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	20	dBm
DC Voltage on any Non-ground Terminal	3	V
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

SF2200E

707 MHz SAW Filter



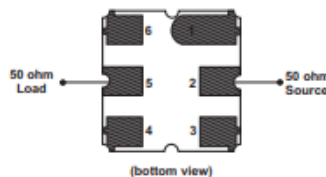
SM3030-6

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f _C			707		MHz
Insertion Loss, 698 to 716 MHz	IL			2.1	3.0	dB
Amplitude Ripple, 698 to 716 MHz				0.5	1.5	
Return Loss, 698 to 716 MHz			7	13		
Attenuation, 0 dB Reference:						dB
10 to 680 MHz			30	50		
745 to 978 MHz			30	42		
978 to 996 MHz			35	58		
996 to 2700 MHz			25	29		
Source Impedance	Z _S			50		Ω
Load Impedance	Z _L			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	930, <u>Y</u> <u>W</u> <u>W</u> <u>S</u>					
Standard Reel Quantity	Reel Size 7 Inch	500 Pieces/Reel				
	Reel Size 13 Inch	3000 Pieces/Reel				

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others

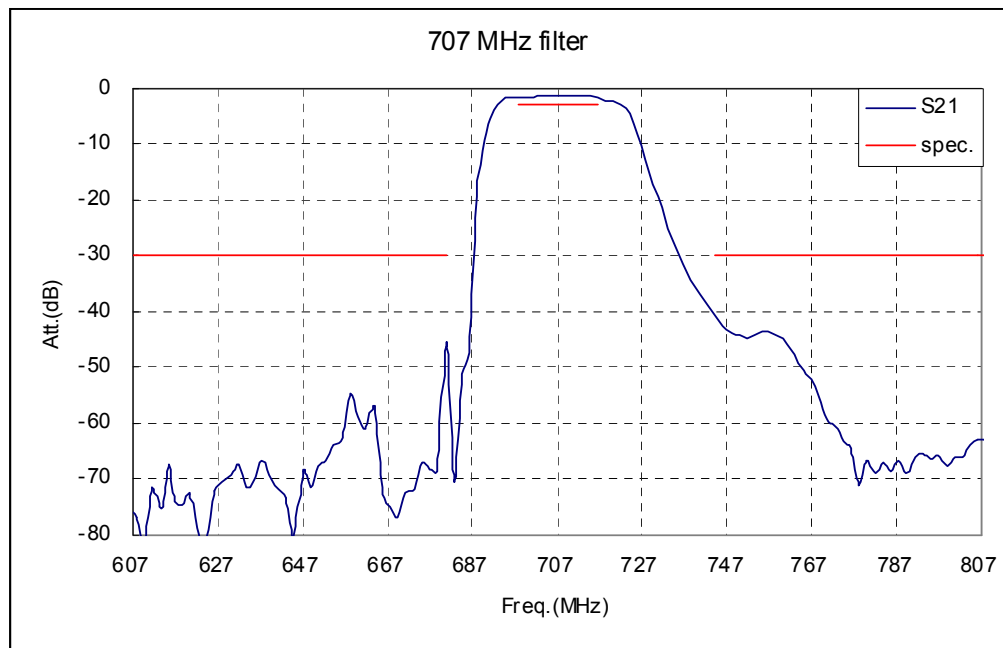
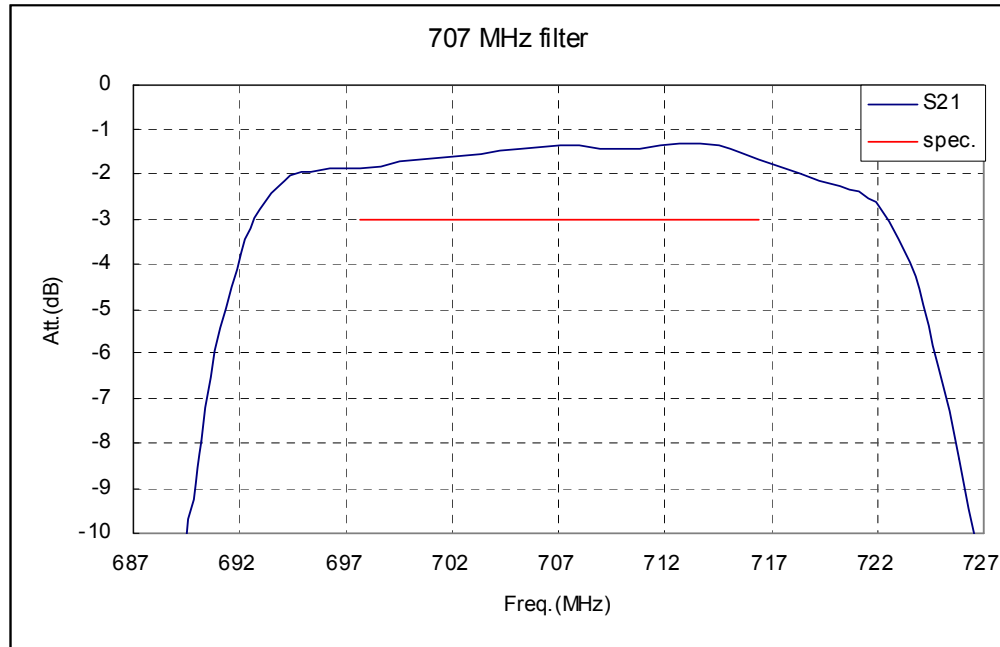


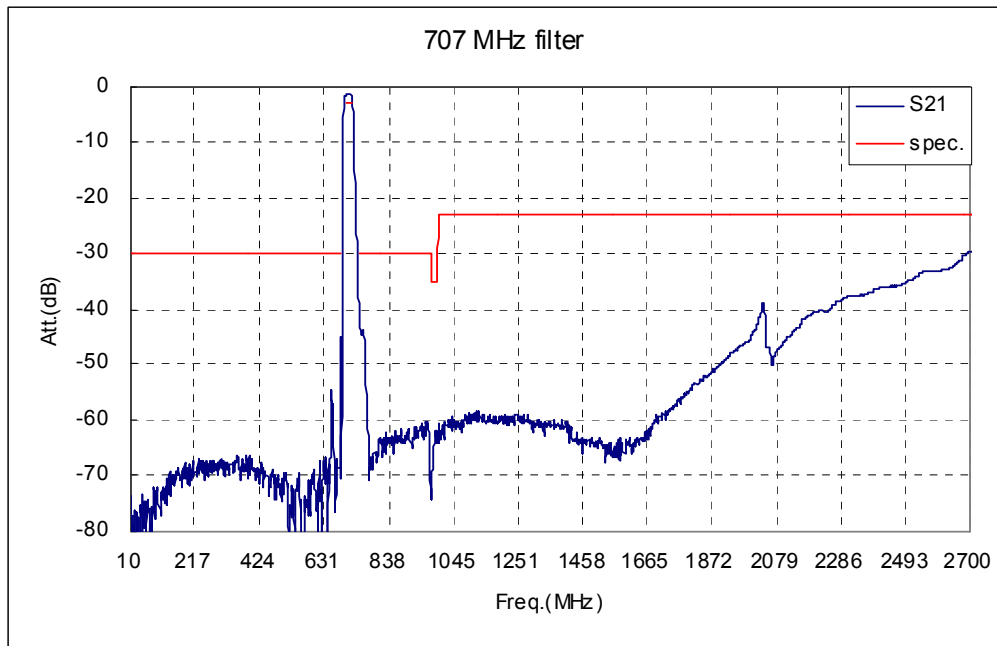
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

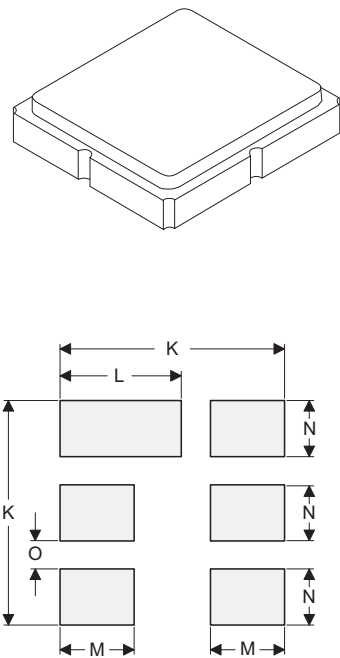
Filter Response Plots





SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

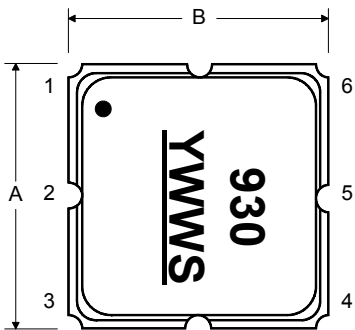
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

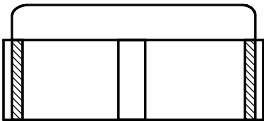
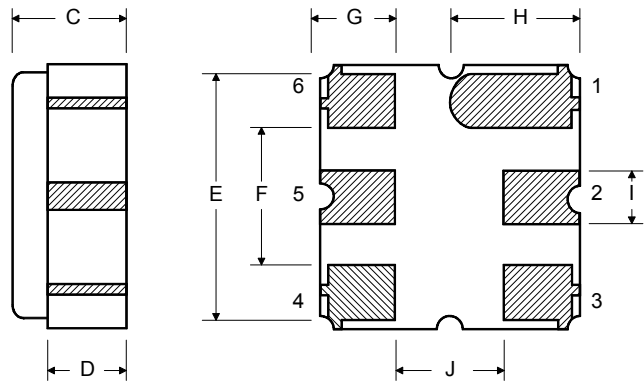
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic
Pb Free	

TOP VIEW



BOTTOM VIEW



See Detail "A"

100 REF.

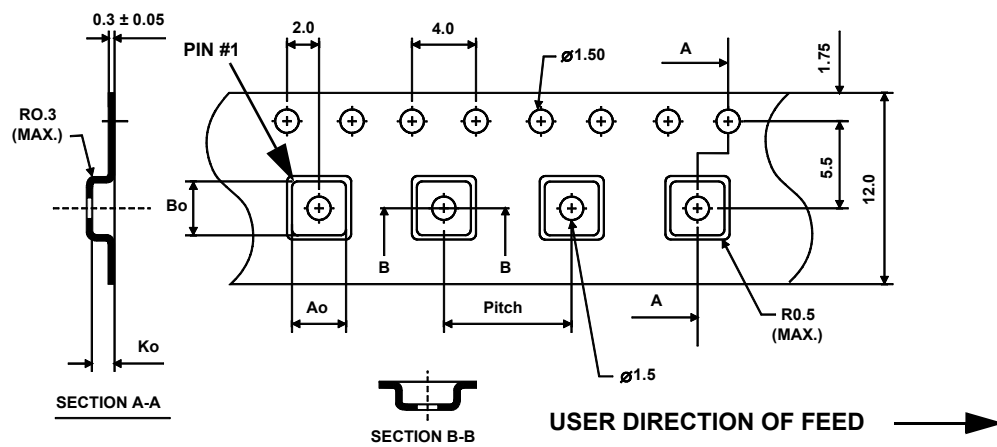
"B" REF.

12.0

The drawing shows a circular component with a central hole. A leader line points from the text "See Detail 'A'" to the central hole. The side view shows a thickness of 12.0 and a reference dimension of 100 REF. for the distance from the center to the outer edge. A reference dimension of "B" REF. is also indicated for the total width.

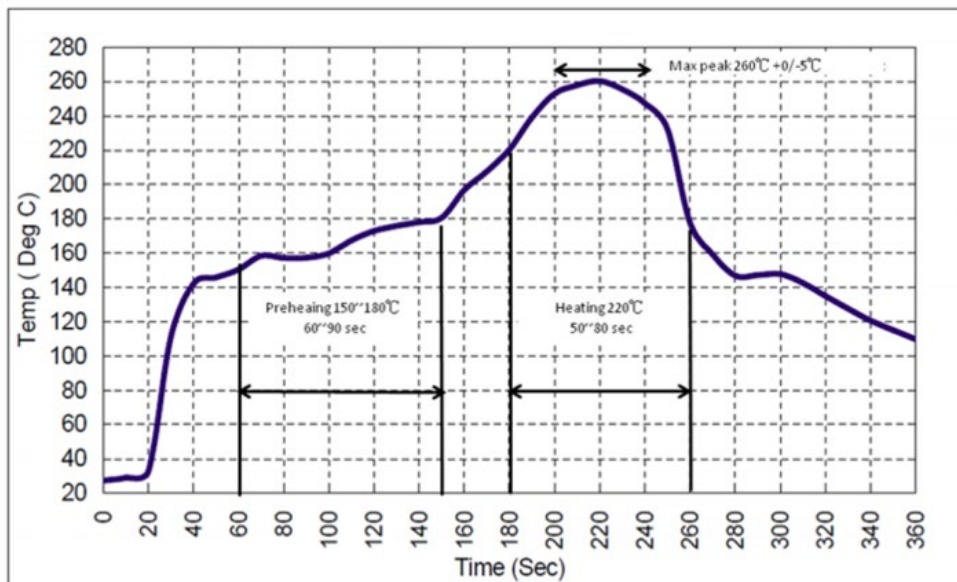
Technical drawing of a circular part. The drawing shows a cross-section of a circular component with a central hole. The outer diameter is labeled as 13.0. The inner diameter is labeled as 20.2. The thickness of the part is labeled as 2.0. The drawing includes a center line and a section line.

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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